SCIENTECH

# 辛耘

許明棋 2025/09/03

# 免責聲明

- 本簡報可能包含對於未來展望的表述。該類表述是基於對現況的預期，但同時又受限於已知或未知的風險與不確定性的影響。因此實際結果將可能不同於表述內容。

- 除法令要求外，公司並無義務因應新資訊的產生或未來事件的發生，主動更新對未來展望的表述。

# 簡報大綱

SCIENTECH

# 公司簡介

**Overview | Milestones | Location | Certificate | Competence**

# 基本資料



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## Product and Technology

- Equipment Design and Manufacturing
- Wafer Reclaim
- Representative

## Industries We Serve

- Semiconductor (Front-End and Advanced Packaging)
- Compound Semiconductor
- LED / Mini LED / Micro LED
- Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)


**Established:**
1979
Taipei, Taiwan

**Capital:**
US$ 27 Million
TWSE:3583

**Employees:**
>1,118
(Worldwide)

# Staffs



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## Over 1,118 Staffs

### Representative

- 140 in Taiwan
- 127 in China
- 70% in Service and Process Support

### Equipment Design and Maf'g

- 442 in Total
- 160+ in R&D, Process and Design

### Wafer Reclaim

- 323 in Total

### Administration

- 86 in Total

# 公司歷程



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1979

**1985**
Branch Office
in Hsinchu, Taiwan

**1995**
Subsidiary
in CA, USA

**2001**
Subsidiary
in Shanghai, China

**2002**
Singapore

**2003**
Equipment Manufacture
Department Established

**2004**
New Hsinchu
Office Opened

**2006**
Wafer Reclaim
Business Launched

**2007**
New Factory
in Hukou Opened

**2013**
Publicly Listed in
Taiwan Stock Market

**2019**
Over 500 Equipment
Sales Achievement

**2021**
Subsidiary
in Villach, Austria

# 台灣據點



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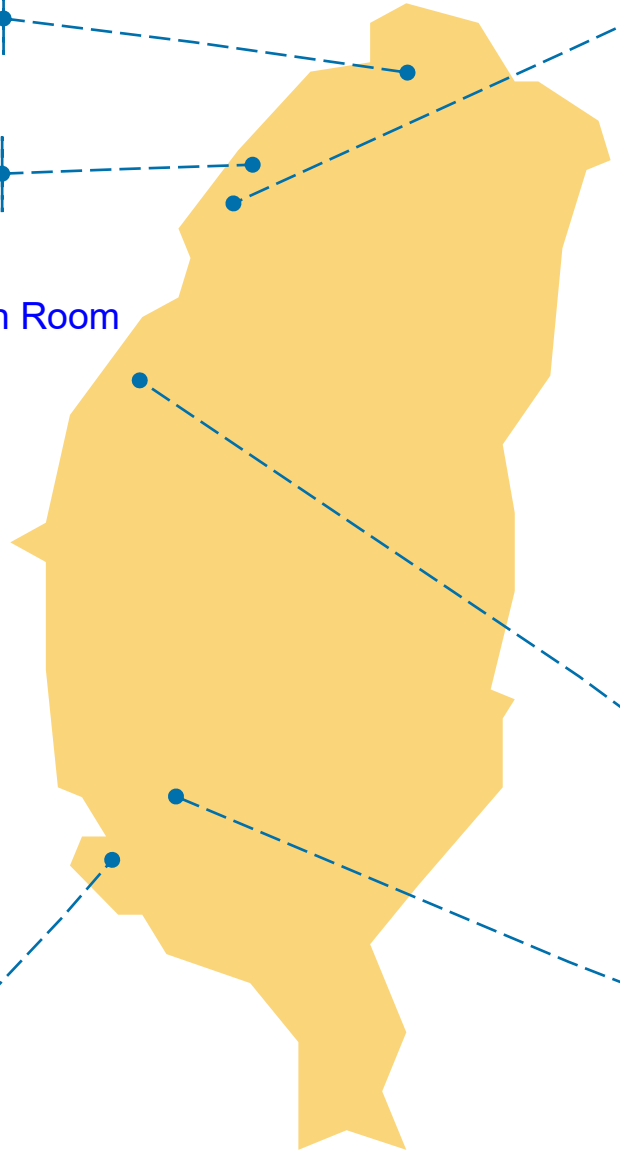
## Taipei Headquarter

## HsinChu Office

## HuKou Factory

- Equipment Design and Manufacturing
  - Equipped With Class 10/1,000/10,000 Clean Room
- Wafer Reclaim



## Taichung Office

## Kaohsiung Office

## Tainan Office

# 國外據點



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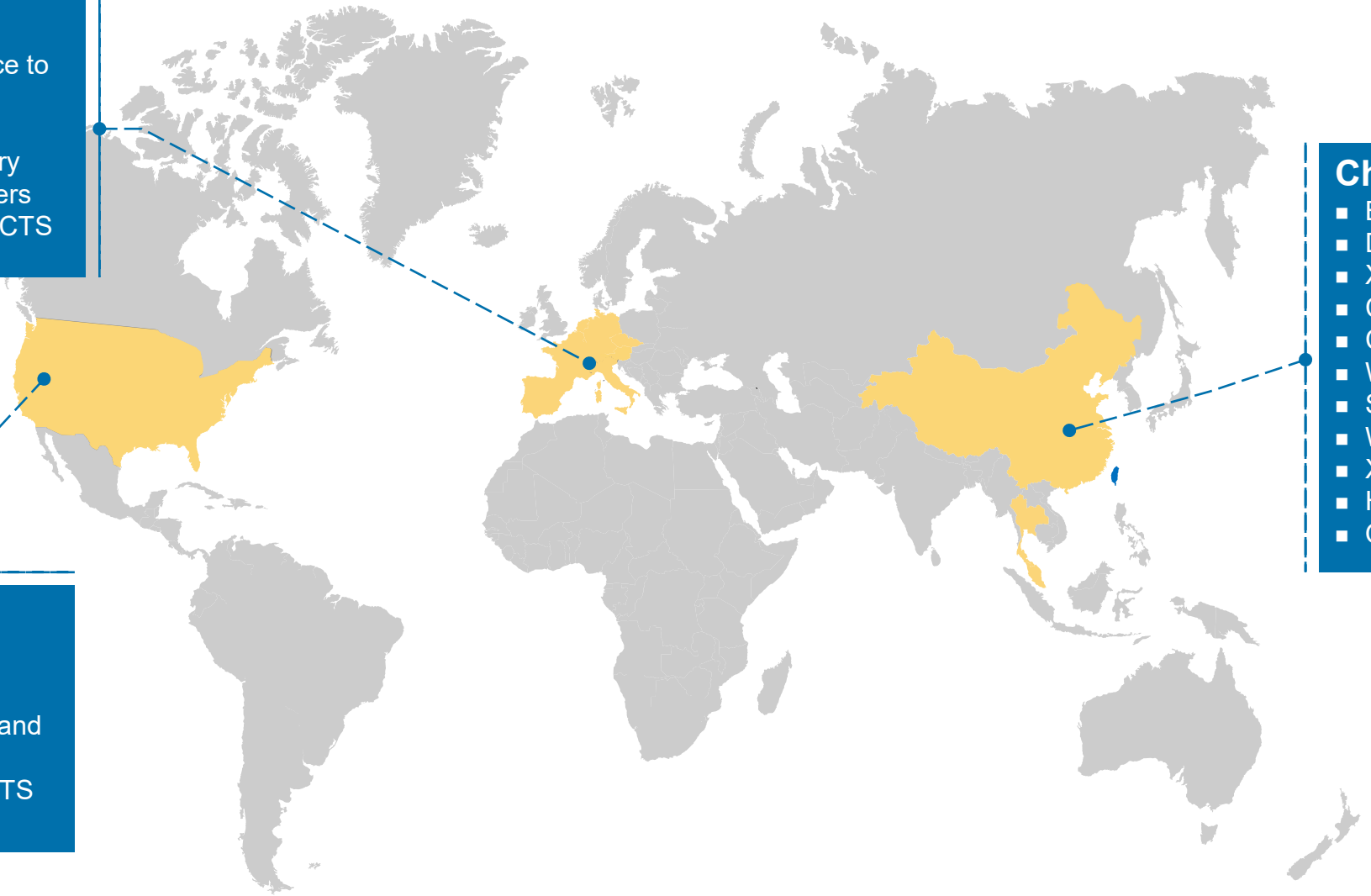
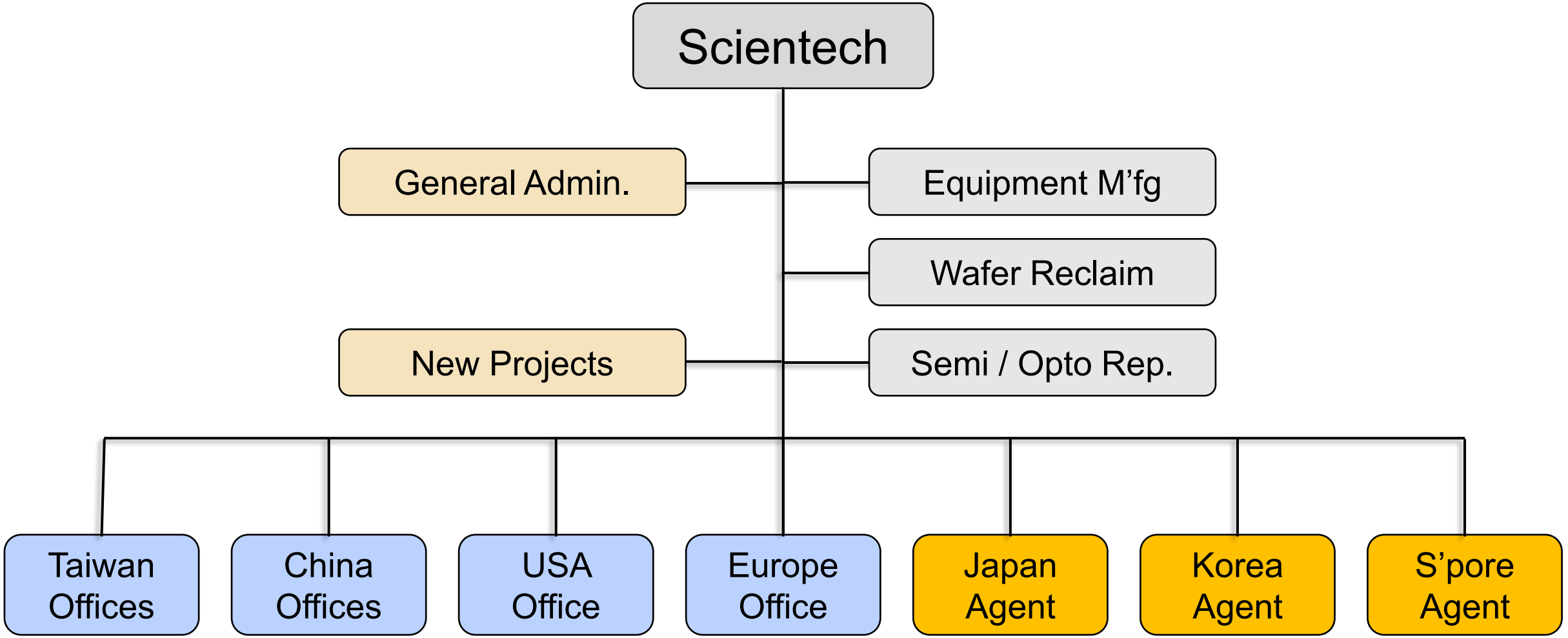
## Europe
Villach, Austria (2020)
- Sales and Service Office to support European customers
- Interface with our factory and European Customers
- New Product / PRODUCTS Development



## China
- Beijing office (2004)
- Dalian office (2012)
- Xian (2013)
- Chongqing office (2010)
- Changzhou (2012)
- Wuxi office (2003)
- Shanghai Office (2001)
- Wuhu office (2013)
- Xiamen office (2011)
- Huizhou office (2013)
- Qunming Office (2002)

## USA
Santa Clara, CA (1994)
- Sales and Service Office
- Interface with Principals and U.S. Customers
- New Product / PRODUCTS Development

# 辛耘公司組織架構

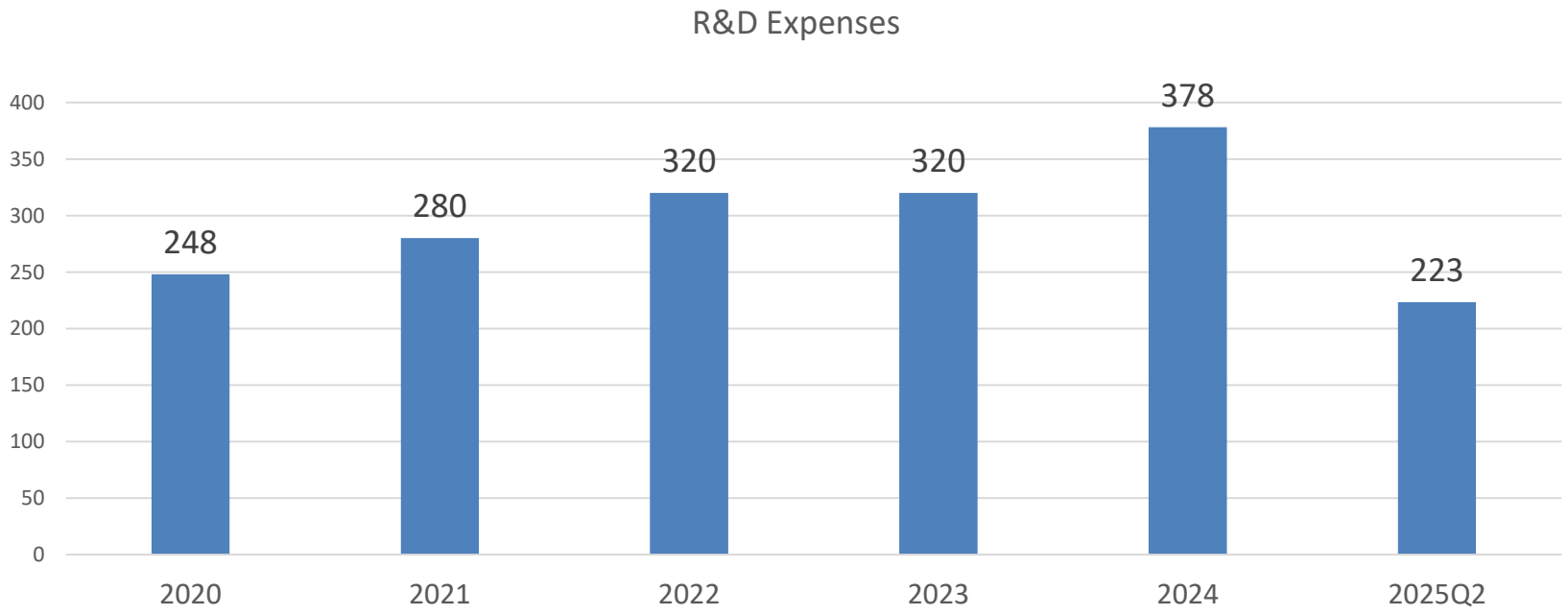

Scientech
General Admin.
Equipment M'fg
Wafer Reclaim
New Projects
Semi / Opto Rep.
Taiwan Offices
China Offices
USA Office
Europe Office
Japan Agent
Korea Agent
S'pore Agent

# 產品與服務

**Wafer Reclaim | Equipment Manufacturing and Design | Representative**

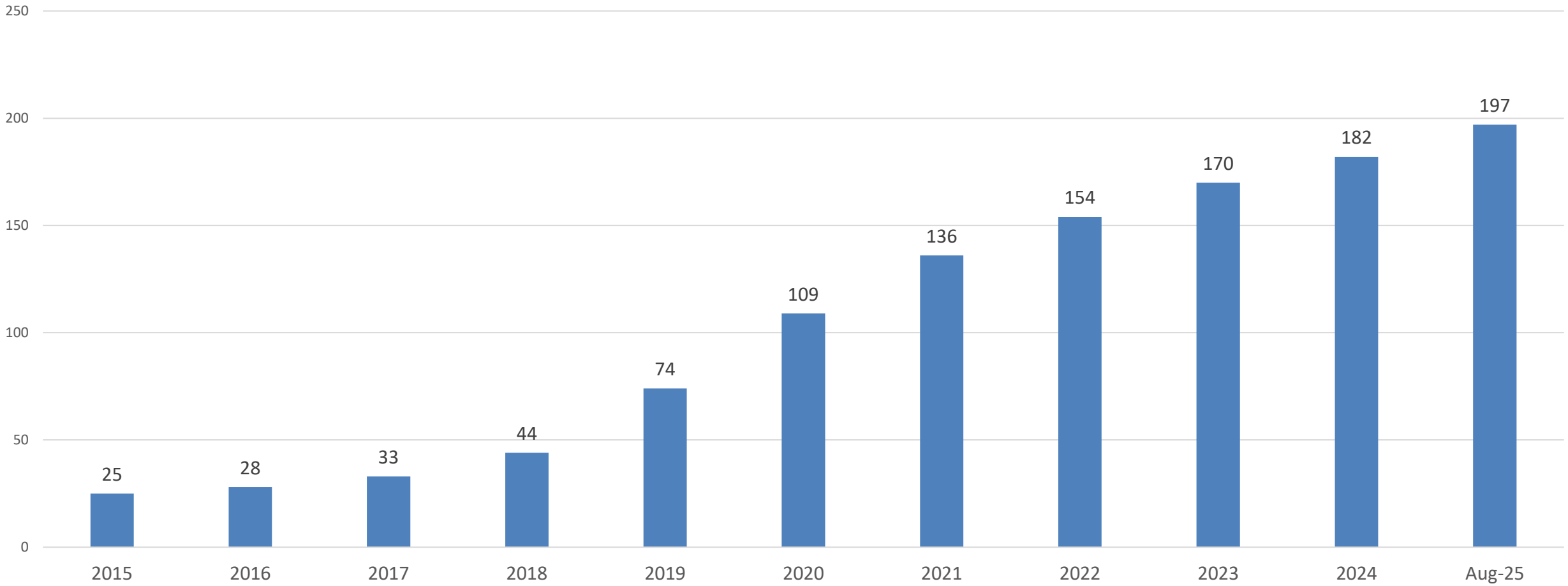
# 研發費用

| 單位：百萬 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025Q2 |
|---|---|---|---|---|---|---|
| 研發費用 | 248 | 280 | 320 | 341 | 378 | 223 |
| 研發費用佔營業收入比重 | 6.9% | 6.0% | 5.7% | 4.9% | 3.9% | 3.9% |
| **研發費用佔製造比重** | | **14.9%** | **15.3%** | **15.7%** | **11.3%** | **9.9%** |



# 研發專利累積數

- **The cumulative number of patents on file is 197, and 49 applications are pending.**



# 產品與服務




## Equipment Design and Manufacturing

- Advanced Package
- FEOL
- Mask
- Compound
- etc...


## Wafer Reclaim

- 12” Si Wafer


## Representative

- Equipment/Metrology
- Sub-System
- Material
- Repair and Refurbish

# 晶圓再生服務



**Advanced Clean Technology**
- 19nm Particle
- Low Trace Metal (<1E9)

**Advanced Defect Inspection (SP1/SP2/SP5/SP7)**

## 12” Si Wafer

- Capacity: 160K / Month
- Cu and Non-Cu Process






## Capacity Expansion

- Additional 50K / Month by end of 2025

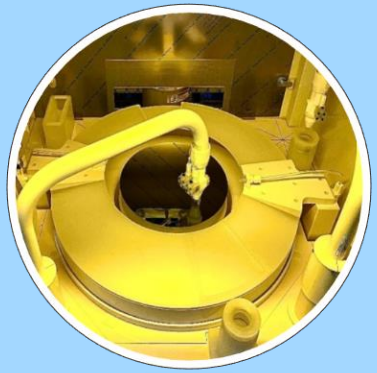
**Complete Polishing Process**
- Single/Double Side Polish
- Final Haze Polish

**Super Flatness (GBIR < 0.5mm)**

# 設備研發及生產



Wet Bench



Single Wafer

TBDB

Baking

# 設備研發及生產



## 批次式濕式製程設備

### Application

- Semiconductor: FEOL, BEOL, Compound
- Advanced Packaging/Bumping…

### Features

- Cassette type or Cassette-less type
- Adopted by big international companies
- Leading-edge technologies

### Process

- Etch: Metal/Oxide/Nitride remove
- Stripper: PR/PI strip, Polymer remove
- Clean: Pre/Post/Flux clean
- Electro-less Plating: Zn/Ni/Pd/Au

# 設備研發及生產



## 單晶圓濕式製程設備

### Application

- Semiconductor: BEOL, FEOL, Compound
- Advanced Packaging/Bumping

### Features

- Soak/Immersion + Single
- Adopted by big international companies
- Leading-edge technologies

### Process

- UBM / Metal Etch
- Flux Clean (Hot DIW)
- PR Strip
- Wafer Clean (APC, Soft spray)
- Final Clean/Mask Clean/Frame Clean

# 設備研發及生產

## 暫時性貼合及剝離設備(TBDB)

### Application

- IGBT & SiC Power Device
- Advanced Packaging for Semiconductor

### Features

- User-friendly graphical user interface
- Adopted by big international companies
- Leading-edge technologies

### Process

- Temporary Bonding
- Temporary De-bonding
- Release Layer Coating
- Carrier (Glass) Recycling

# 設備研發及生產

## 水氣烘烤設備

### Application

- Semiconductor: BEOL
- Advanced Packaging for Semiconductor

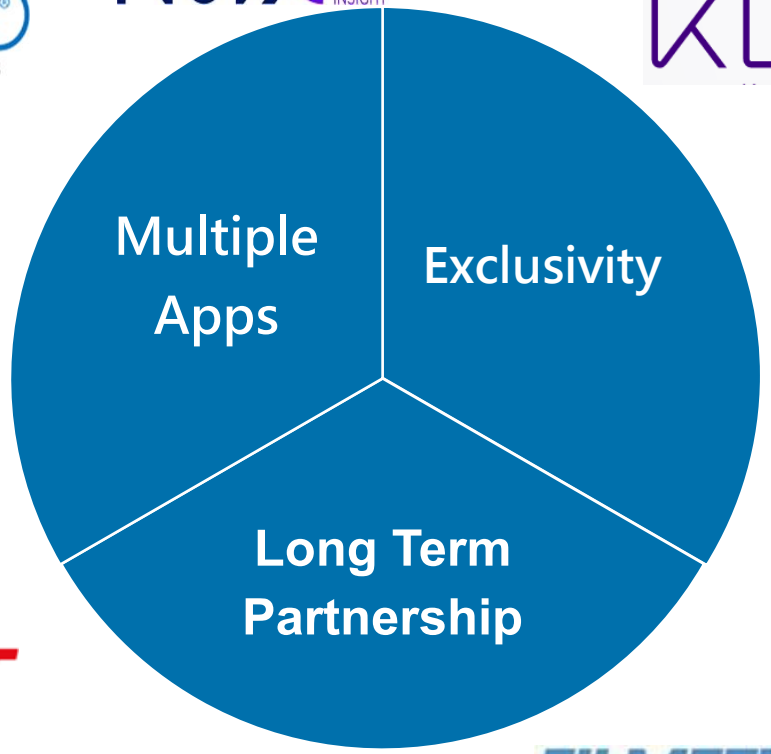
### Features

- Availability for horizontal or vertical process
- High precision temperature control
- Weight handling capacity up to 23kg per lot

### Process

- Pre-underfill baking
- Pre-mold baking
- DFR Hard Bake

# 代理事業



# 代理產品

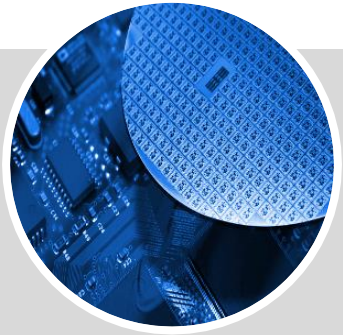


## Lithography

- KINGSEMI
- SMEE
- vistec Electron Beam
- ESOL
- USHIO

## Etch

- Plasma-Therm
- CORIAL
- Trymax PLASMA TECHNOLOGY SOLUTIONS
- NEMS tek GLOW THE FUTURE
- Verity INSTRUMENTS, INC.



## Thin Film

- ClassOne TECHNOLOGY
- IntlVAC THIN FILM
- ProOptics
- AXUS TECHNOLOGY

## Diffusion

- HPSP High Pressure Solution Provider

# 代理產品



## Metrology

KLA
FILMETRICS
ZEISS
Camtek
VLSI Standards Incorporated
MueTec Measurement and Inspection
SURUGA SEIKI
YAYATECH
Rigaku
Toho Technology

## Sub-Systems

Advanced Energy
MDC PRECISION
TMC / AMETEK
Verity INSTRUMENTS, INC.
CORE INSIGHT 코어인사이트(주)
UNEO
AMETEK
Haydon kerk Motion Solutions
PITTMAN

## Package & Material

PacTech
sempro
SANYOSEIKO CO.,LTD.
MIRTEC
MODU TECH
GP 群翊 GROUP
M Napra
AMC Quality & Service
Cygnus
Univertical Global Benchmark of Quality

## Robot Repair and Refurbish

Genmark
Kensington LABORATORIES
MILARA
Dynatronix

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# 公司治理

# 國際標準認證



**2007 — ISO 9001**

Quality Management

**2010 — ISO 14001**

Environmental Management

**2016 — TIPS**

Taiwan Intellectual Property Management

**2018 — ISO 45001**

Occupational Health and Safety Management

**2019 — ISO 27001**

Information Security Management

**2021 — ISO 22301**

Business Continuity Management

**2022 — RBA**

Responsible Business Alliance Online Member

**2024 — ISO 50001**

Energy Management

# ESG永續發展

## 發行永續報告書


E 環境友善

S 溫馨職場

S 回饋社會

G 誠信經營

# Exhibition



SEMICON®

**Semicon China**

Mar. 26-28, 2025
Shanghai

SEMICON®

**Semicon TW**

Sep. 10-12, 2025
Taipei

SEMICON®

**Semicon West**

Oct. 07–09, 2025
Phoenix

SEMICON®

**Semicon Europa**

Nov. 18-21, 2025
Munich

# Exhibition



**ISES**

May 13-14, 2025
Taipei

**ECTC**

May 27-30, 2025
Dallas, Texas

# 營運概況

# 簡明損益表

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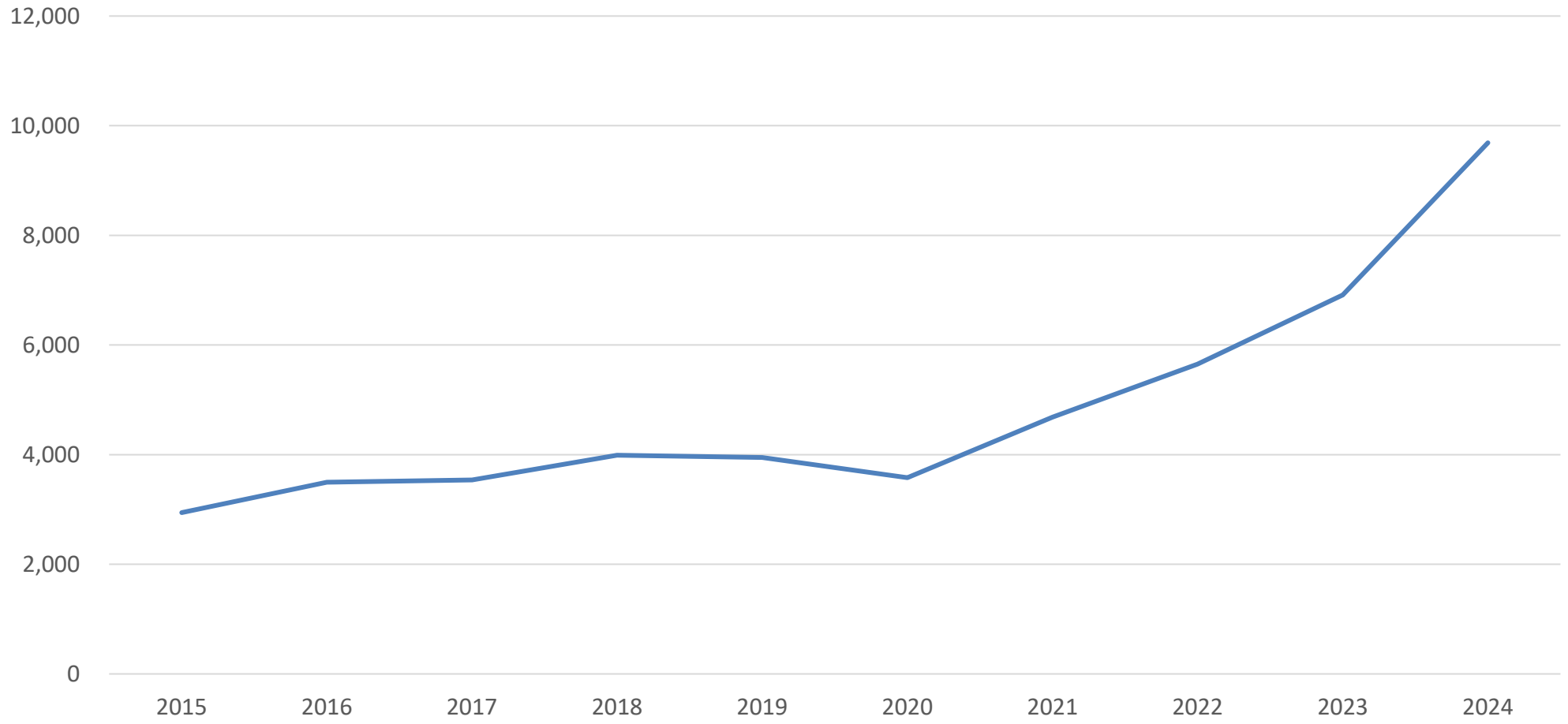
| Units：NT $ M | 2020 | 2021 | 2022 | 2023 | 2024 | 2025Q2 |
|---|---|---|---|---|---|---|
| Revenues | 3,580 | 4,684 | 5,650 | 6,911 | 9,688 | 5,726 |
| Gross Profit | 1,456 | 1,667 | 2,084 | 2,201 | 2,906 | 1,858 |
| Operating Expenses | 991 | 1,112 | 1,374 | 1,483 | 1,790 | 1,038 |
| Operating Income | 465 | 555 | 710 | 718 | 1116 | 819 |
| Income Before Tax | 389 | 524 | 736 | 860 | 1277 | 650 |
| Net Income | 305 | 420 | 568 | 650 | 927 | 486 |
| **EPS** | **3.80** | **5.23** | **7.08** | **8.10** | **11.54** | **6.05** |
| Gross Margin | 41% | 36% | 37% | 32% | 30% | 32% |
| Operating Margin | 13% | 12% | 13% | 10% | 12% | 14% |
| Income Before Tax Margin | 11% | 11% | 13% | 12% | 13% | 11% |

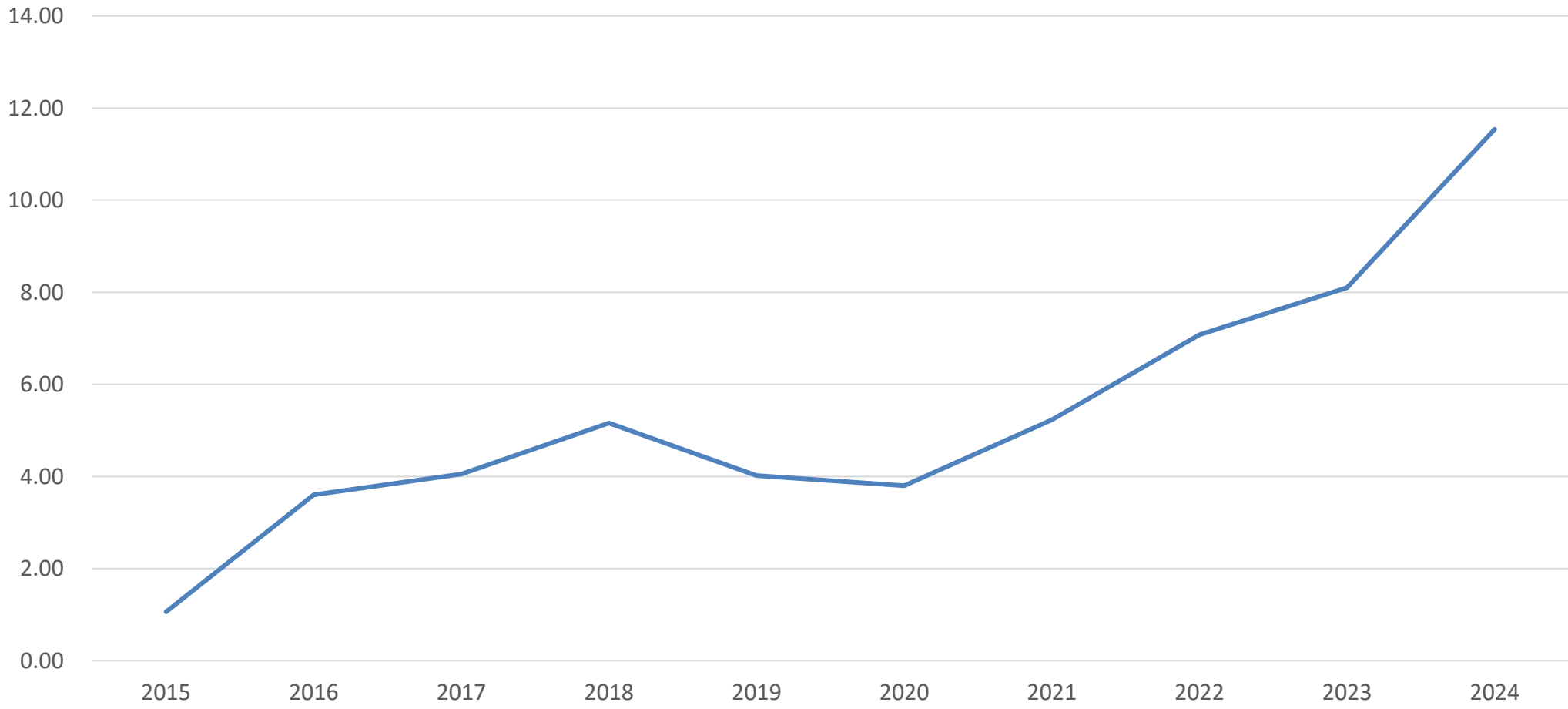
# 歷年營收

| Units NT $ M | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025Q2 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| Revenue | 2,942 | 3,495 | 3,539 | 3,988 | 3,949 | 3,580 | 4,684 | 5,650 | 6,911 | 9,688 | 5,726 |



# 歷年 EPS

| | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025Q2 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| EPS | 1.06 | 3.6 | 4.05 | 5.16 | 4.02 | 3.8 | 5.23 | 7.08 | 8.1 | **11.54** | **6.05** |



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# 未來展望

# 總體市場方向

- The CAGR of the Semi. market size over the next 10 years is approximately 8%
- In 2025, the global Semi. market is expected to grow 11%
- Driven by demand in artificial intelligence (AI) and high-performance computing applications, the semi. market in Taiwan:

| Year | Market Size (Billion US$) | Groth Rate (%) |
|---|---|---|
| 2024 | 165 | 22 |
| 2025 | 187 | 16.5 |

- 12-inch semi. advanced process continues to thrive
  - Front-End: 5nm、3nm、2nm、1nm
  - Advanced Package: Fan-Out、2.5D (CoWoS)、3D (SoIC)…etc

# 總體市場方向– 2

- The CAGR of Advanced Packaging over the next 10 years is estimated at 11%.
- CoWoS production capacity is expanding substantially to meet the rising demand for AI chip applications
- AI applications are expanding from data centers to personal devices
- China's semi. production capacity is expanding, intensifying price competition in mature process nodes.
- Compound Semi:
  - Investment in electric vehicles (EVs) and 5G is stagnant
  - Mobile phone demand is saturating, leading to reduced GaAs production
  - SiC demand gradually increases, with new capacities slowing down
  - Micro LED adoption is progressing slowly

# 擴產計畫

- 2023: New equipment production base in Hukou (off-site)
- 2024: Expansion of existing equipment production at Hukou Plant
- **2025 Q4: Wafer Reclaim Capacity 50K/Month at Hukou Plant**
- **2026 Q4: 9,000 M-Square new building (Plant II) for equipment manufacturing, and warehouse next to Hukou Plant (Plant I)**
- **2026 Q4: Wafer Reclaim Capacity 30K/Month at Hukou Plant**
- **2027 Q1: 20,000 M-Square new building for equipment manufacturing, and warehouse in Tainan (southern Taiwan)**
- 2027: Wafer Reclaim Capacity 50K/Month at Hukou Plant

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# Thank You!

https://www.scientech.com.tw